

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Efren M. Lacap et al.

Confirmation No.: 4089

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Examiner: Jonathan J. Johnson

Title: WAFER-LEVEL CHIP SCALE
PACKAGE

Attorney Docket No.: 408204

June 4, 2007

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT UNDER 37 C.F.R. § 41.33

Sir:

In accordance with 37 C.F.R. § 41.33, Applicants present the following amendments to the application:

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 6 of this paper.